

UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Solderable per MIL-STD-202, Method 208 @

Weight: 0.0009 grams (Approximate)

Case Material: Molded Plastic. "Green" Molding Compound.

Product Summary

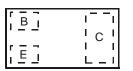
Part Number	R1 (NOM)	Marking
DDTC113TLP	1kΩ	N4

Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

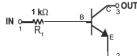
X1-DFN1006-3





Bottom View

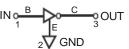
Top View Pin-Out



Mechanical Data

Case: X1-DFN1006-3

Terminals: Finish - NiPdAu



-Ó GND

Device Symbol

Equivalent Inverter Circuit

Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTC113TLP-7	N4	7	8	3,000
DDTC113TLP-7B	N4	7	8	10,000

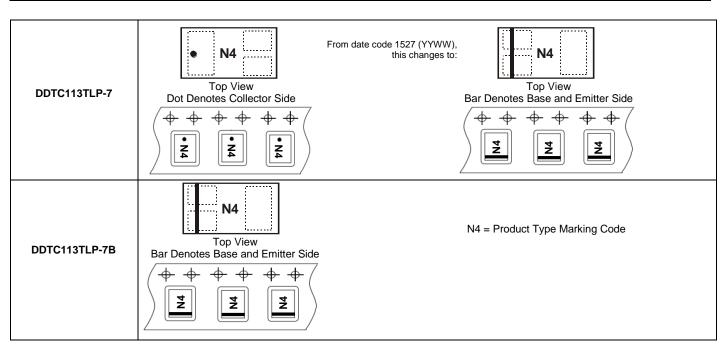
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	50	V
Input Voltage	V _{IN}	-5 to +10	V
Output Current (I _O)	I _{C(MAX)}	100	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

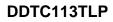
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	250	mW
Power Derating above +25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5) (Equivalent to one heated junction of NPN)	R _θ JA	500	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

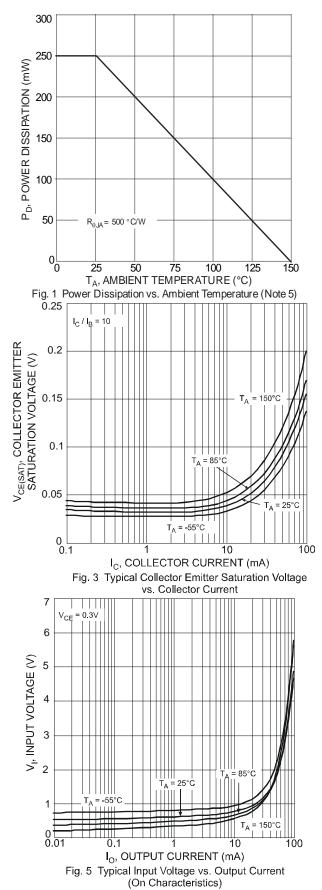
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

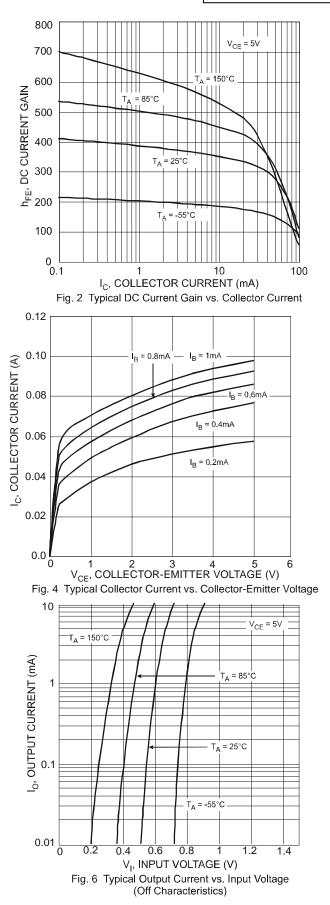
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Collector-Base Breakdown Voltage	BV _{CBO}	50	_		V	$I_{\rm C} = 50 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	50	_		V	$I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	5	_		V	$I_{E} = 50 \mu A, I_{C} = 0$
Collector-Base Cutoff Current	I _{CBO}			0.1	μA	$V_{CB} = 50V, I_E = 0$
Emitter-Base Cutoff Current	I _{EBO}			0.1	μA	$V_{EB} = 4V, I_{C} = 0$
ON CHARACTERISTICS (Note 6)	·					-
DC Current Gain	h _{FE}	100	380	600	_	$V_{CE} = 5V, I_C = 1mA$
Collector-Emitter Saturation Voltage	V _{CE(sat)}			0.25	V	I _C = 50mA, I _B = 2.5mA
Input Resistance	R1	0.7	1	1.3	kΩ	_
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f⊤		250	_	MHz	V _{CE} = 10V, I _E = 5mA, f = 100MHz

 For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%. Notes:





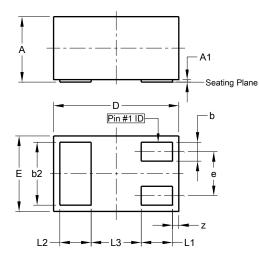






Package Outline Dimensions

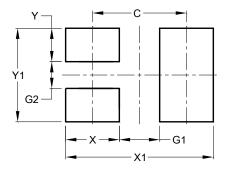
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-3				
Dim	Min	Max	Тур	
Α	0.47	0.53	0.50	
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.075	1.00	
Е	0.55	0.675	0.60	
e	1	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	1	-	0.40	
Z	0.02	0.08	0.05	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Ý	0.25
Y1	0.70



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